

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

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Sheet 1 of 4

Complete if Known

Application Number	09/874,631
Filing Date	June 5, 2001
First Named Inventor	Moon et al.
Group Art Unit	2815
Examiner Name	S. Clark
Attorney Docket Number	2269-4368US (99-0959.00/US)

U.S. PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
<i>SW</i>		US-3,239,496	03/1966	Jursich	
<i>SW</i>		US- 4,074,342	02/1978	Honn et al.	
<i>SW</i>		US- 4,818,728	04/1989	Rai et al.	
<i>SW</i>		US- 5,148,265	09/1992	Khandros	
<i>SW</i>		US- 5,348,881	09/1994	Khandros	
<i>SW</i>		US- 5,404,044	04/1995	Booth et al.	
<i>SW</i>		US- 5,468,681	11/1995	Pasch	
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<i>SW</i>		US- 5,742,100	04/1998	Schroeder et al.	
<i>SW</i>		US- 5,777,391	07/1998	Nakamura	
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<i>SW</i>		US- 6,133,837	10/2000	Hikita et al.	
<i>SW</i>		US- 6,177,723	01/2001	Eng et al.	
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<i>SW</i>		US- 6,222,285	04/2001	Akram et al.	

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Examiner Initials *	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁴
		Country Code ³ - Number ⁴ - Kind Code ⁵ (if known)				
<i>SW</i>		EP 0684644	11.1995	Kata et al.		
<i>SW</i>		EP 1009027	06/2000	Okuno		
<i>SW</i>		KR 2001054744	07/2001	Choi et al. (English Abstract)		

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Sheet	2	of	4
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		Number - Kind Code² (if known)			
SU		US- 6,232,666	05/2001	Corisis et al.	
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Examiner Name	S. Clark
Attorney Docket Number	2269-4368US (99-0959 00/US)

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
gk		AL-SARAWI et al., "A review of 3-D packaging technology," Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging, Vol 21, Issue 1, Feb. 1998, pp. 2-14.	
gk		ANDROS et al., "TBGA Package Technology," Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging, Vol. 17, Issue 4, Nov. 1994, pp. 564-568.	
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gk		HAUG et al., "Low-Cost Direct Chip Attach: Comparison of SMD Compatible FC Soldering with Anisotropically Conductive Adhesive FC Bonding," IEEE Transactions on Electronics Packaging Manufacturing, Vol. 23, No. 1, Jan 2000, pp. 12-18.	
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Examiner Name	S. Clark
Attorney Docket Number	2269-43681US (99-0959 00/1S)

OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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gnc		XIAO et al., "Reliability study and failure analysis of fine pitch solder-bumped flip chip on low-cost flexible substrate without using stiffener," <i>IEEE</i> , 2002. Proceedings 52 nd , 28-31 May 2002, pp. 112-118.	

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